

ABSTRACT

Please replace the paragraph at page 25, lines 2 to 7, with a replacement paragraph amended as follows:

A method of manufacturing single-crystal semiconductor wafers is characterized in that a plurality of single-crystal semiconductor wafers of a relatively small diameter $[(\frac{1}{2}a-2d)]$ desired by users are cut out from a single-crystal semiconductor wafer of a relatively large ~~diameter (1a-1d)~~ diameter. Therefore, there can also be obtained a secondary effect that even if the large-scale single-crystal semiconductor wafer has defective parts, the small-scale wafers cut out from the non-defective parts can be shipped to the market.